

Day 1 - Monday 15th April 2024

18:30 Pre-conference networking drinks reception

Day 2 - Tuesday 16th April 2024

- 08:00 Registration and welcome refreshments
- 08:50 Housekeeping by Chris Meadows and Tim Bettles Conference Chairs

Ensuring SiC's phenomenal success

| 09:00 | Silicon Carbide: a game changer in power electronics |
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| 09:15 | Presented by Mario Saggio - STMicroelectronics Supporting SiC Success Stories Through Technical Innovation |
| 09:30 | Presented by David Liese - htt Group, and Michael Köppl - htt Group Next-Generation Factory Inspection: Improving Performance by Synthesizing Intelligent Microscopy |
| 07.50 | Presented by Marius Fischer - Nanotronics Challenges in HVM Amidst Evolving Device Architectures and Requirements for Compound Semiconductor based Power |
| 09:45 | Devices Presented by Nick Keller - Onto Innovation |
| 10:00 | Sharpening SiC Wafer specs and Frontend Performance by Crystal Orientation Metrology |
| 10:15 | Presented by Lars Grieger - Malvern Panalytical Sample preparation and TEM imaging techniques for advanced power device analysis |
| 10:30 | Presented by Antonio Mani - Thermo Fisher Scientific Morning Break |
| 10.50 | |
| 11:10 | Giving SiC a superjunction Presented by Reza Ghandi - GE Aerospace |
| 11:25 | The Unspoken Impacts of SiC Power Packaging Presented by Kevin Speer - Microchip |
| 11:40 | Challenges and solutions in new generation SiC metrology Presented by Dr. Eszter Najbauer - Semilab |
| 11:55 | Accelerating semiconductor technologies for the green revolution Presented by Shiva Rai - Applied Materials |
| 12:10 | A Hybrid Defect Inspection System for SiC substrate and Epi applications Presented by Aris Ma - AK Optics Technology Co. Ltd |
| 12:25 | Capital Efficient Systems for SiC Manufacturing Expansion and R&D Presented by Brian Stickney - C & D Semiconductor |
| 12:40 | Lunch Break |
| 13:55 | Enabling Low Cost SiC Boule Fabrication – The BoulePro 200AX is the New Process Of Record |
| 14:10 | Presented by Jeff Gum - Usach Industry ready detection of TSDs and BPDs in SiC wafers |
| 14:25 | Presented by DrIng. Christian Reimann - Rigaku Cutting-edge SiC Manufacturing: Beyond Chemical-Mechanical Constraints |
| 14:40 | Presented by Philipp Böttger - scia Systems GmbH Modernizing Industrial Low Voltage Motor Drives with Silicon Carbide |
| 14.40 | Presented by Pranjal Srivastava - Wolfspeed PulseForge and Teikoku Taping Systems Announce Novel Fully Automated Photonic Debonding Platform |
| 14:55 | Presented by Vahid Akhavan - PulseForge (in association with Teikoku Taping Systems Inc) |
| 15:10 | Coating at its best - Spraying graphite parts with tantalum carbide cuts the cost of producing SiC crystals |
| 15.25 | Presented by DrIng. Matthias Trempa - Fraunhofer IISB Powering the SiC Revolution with Vertical Integration |
| 15:25 | Presented by Ajay Poonjal Pai - Sanan |
| 15:40 | Afternoon Break |
| Taking po | ower from the photon |
| 16:20 | Record-breaking solar cells Presented by Dr. Oliver Höhn - Fraunhofer ISE |
| 16:35 | Integrated storage unlocks CPV's full potential Presented by Kira Rundel - RayGen |
| 16:50 | Germanium Substrates for Photonics and PV: Ensuring Supply Security, Advancing Recycling and Enabling CMOS integration Presented by Ivan Zyulkov - Umicore |
| 17:05 | Lattice-matched III-V solar cells. Progress and application opportunities Presented by Prof. Mircea Guina - Tampere University |
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- 17:20 Development of far-UVC LEDs for sensing and skin tolerant antisepsis *Presented by Sven Einfeldt - FBH Berlin*
 17:35 Heterogenous Integration of Compound Semiconductors by W2W and D2W Bonding *Presented by Dr. Bernd Dielacher - EV Group*
 17:50 Making monolithic RGB displays with InGaN *Presented by WonTaeg Lim - Soft-Epi*
- 18:05 Closing Remarks
- 18:10 Networking Drinks / Dinner Reception

Day 3 - Wednesday 17th April 2024

08:00 Registration and welcome refreshments

08:50 Housekeeping by Chris Meadows and Tim Bettles - Conference Chairs

| Accelera | ating the growth of GaN Sponsored by Precision Fabricators |
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| 09:00 | Where will GaN Power Semiconductors find their greatest success in the 2020s? Presented by Richard Eden - Omdia |
| 09:15 | The strengths of IC enhancement-mode GaN Presented by Andrea Bricconi - Cambridge GaN Devices |
| 09:30 | Presentation Title to be Confirmed |
| 09:45 | Harnessing the Power of RF GaN-on-Si Technology for Next Generation Connectivity <i>Presented by Nadine Collaert - imec</i> |
| 10:00 | Accelerating the Growth of GaN-based Power Electronics Via Adoption of 300mm Technology Presented by Rudy Parekh - Veeco |
| 10:15 | Next Level Epitaxy: Revolutionizing Mass Production of Wide Bandgap Semiconductors Presented by Dr. Yilmaz Dikme |
| 10:30 | Morning Break |
| 11:10 | Considerations for Tool-To-Tool Matching Across a Fleet of Metrology Tools Presented by Tamzin Lafford - Bruker UK |
| 11:25 | Connected metrology – Full 2D characterization of HEMT device structure epi-wafers <i>Presented by Johannes Zettler - LayTec AG</i> |
| 11:40 | Emerging Growth Opportunities for MBE in GaN Presented by Brian Miller - Riber |
| 11:55 | Commercialization of buffer-free GaN on SiC materials for defense, space, telecom markets and beyond <i>Presented by Jr-Tai Chen - SweGaN</i> |
| 12:10 | Numerical design propels RF and power GaN technology Presented by Ahmed Nejim - Silvaco |
| 12:25 | Solving the EMC and thermal issues of driving GaN at high speed Presented by Rupert Baines - QPT |
| 12:40 | GaN: Delivering on the Net-Zero Economics of an AI-Enabled Future Presented by Peter Rabbeni - IQE |
| 12:55 | Lunch Break |
| Expandi | ing horizons for surface emitters |
| 14:10 | VCSELs: Driving Innovations in 3D Sensing and Data Communication Presented by Ali Jaffal - Yole Group |
| 14:25 | Vertilas InP VCSELs to address fast growing and novel applications at and beyond 1.3 Im Presented by Christian Neumeyr - Vertilas |
| 14:40 | Expanding the scope of VCSELs through wavelength extension, added functionality and high power density <i>Presented by Julien Boucart - Coherent</i> |
| 14:55 | Speeding VCSEL feedback Presented by Jack Baker - ICS |
| 15:10 | Building, powerful, blue-surface-emitting SLEDs Presented by Juan Morales - iSLight |
| 15:25 | Novel high-power VCSEL laser modules for Battery Manufacturing Presented by Roman Koerner - TRUMPF |
| 15:40 | Placing photonic crystal nano-lasers to silicon Presented by Mingchu Tang - University College London |
| 15.55 | Closing Remarks |

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